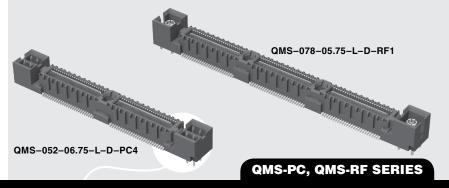




(0.635 mm) .025"



HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material:

Liquid Crystal Polymer Terminal & Ground Plane Material:

Phosphor Bronze

Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Signal Contact: 2.6 A per pin

(2 pins powered) Power Contact: 4.0 A per pin (4 pins powered per end) Ground Plane:

15.7 A per ground plane (1 ground plane powered)

Voltage Rating:
300 VAC mated with QFS Operating Temp: -55 °C to +125 °C

RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

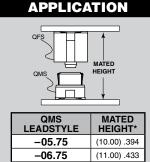


ALSO AVAILABLE (MOQ Required)

- · Other platings
- Differential Pairs
- Retention Pins
- 8 Power Pins/End for (1.60 mm) 0.62" thick board
- · 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- Hot Pluggable

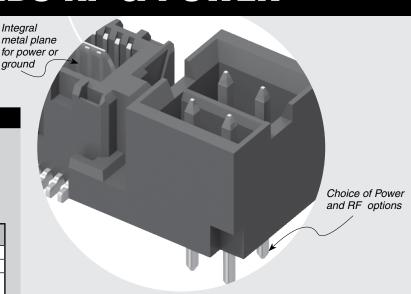
Some lengths, styles and options are non-standard, non-returnable.





*Processing conditions will affect mated height. See SO Series for board space tolerances

QMS





NO. OF PINS

PER ROW

LEAD Α STYLE (5.38)05.75 .212 (6.35) 06.75

Specify LEAD STYLE from chart

LEAD

= 10 µ" (0.25 µm) Gold on Signal Pins and Ground Plane

PLATING

OPTION

(Tin on Signal Pin tails, and Ground Plane tails)

-PC4 = 4 Power

END

OPTION

Pins per End for (1.60 mm) .062 thick Board (not available with -RF1)

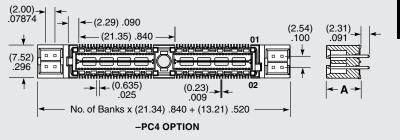
–RF1 = One RF Plug per End (-05.75 only, not available with -PC4)

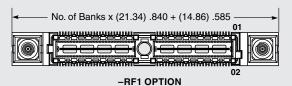
-TR

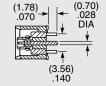
=Tape & Reel

-FR = Full Reel Tape & Reel (must order max quantity per reel; contact Samtec

for quantity breaks)









OTHER